

TinyLogic ULP-A Buffer with Schmitt-Trigger Input

NC7SP17

The NC7SP17 is a single buffer with Schmitt-Trigger Input in tiny footprint packages. The device is designed to operate for $V_{CC} = 0.9\text{ V}$ to 3.6 V .

Features

- Designed for 0.9 V to 3.6 V V_{CC} Operation
- 2.6 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 2.6 mA at 3.3 V
- Available in SC-88A and MicroPak™ Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

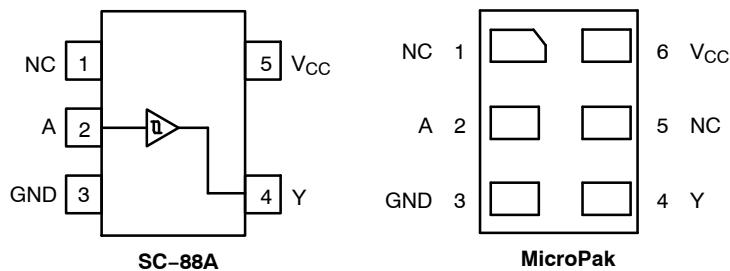


Figure 1. Pinout Diagrams (Top Views)

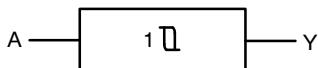


Figure 2. Logic Symbol

PIN ASSIGNMENT

Pin	SC-88A	MicroPak
1	N.C.	N.C.
2	A	A
3	GND	GND
4	Y	Y
5	V_{CC}	N.C.
6	—	V_{CC}

N.C. = No Connect

FUNCTION TABLE

Input	Output
A	Y
L	L
H	H

X = Don't Care
Z = High Impedance State

MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
V_{CC}	DC Supply Voltage	-0.5 to +4.3	V
V_{IN}	DC Input Voltage	-0.5 to +4.3	V
V_{OUT}	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)	-0.5 to $V_{CC} + 0.5$ -0.5 to +4.3 -0.5 to +4.3	V
I_{IK}	DC Input Diode Current $V_{IN} < GND$	-50	mA
I_{OK}	DC Output Diode Current $V_{OUT} < GND$	-50	mA
I_{OUT}	DC Output Source/Sink Current	± 50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin	± 50	mA
T_{STG}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	+150	°C
θ_{JA}	Thermal Resistance (Note 2) SC-88A MicroPak	377 154	°C/W
P_D	Power Dissipation in Still Air SC-88A MicroPak	332 812	mW
MSL	Moisture Sensitivity	Level 1	-
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3) Human Body Model Charged Device Model	2000 1000	V
$I_{Latchup}$	Latchup Performance (Note 4)	± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Positive DC Supply Voltage	0.9	3.6	V
V_{IN}	DC Input Voltage	0	3.6	V
V_{OUT}	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)	0 0 0	V_{CC} 3.6 3.6	
T_A	Operating Temperature Range	-40	+85	°C
t_r, t_f	Input Transition Rise and Fall Time	0	No Limit	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.



DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			T _A = -40°C to +85°C		Unit
				Min	Typ	Max	Min	Max	
V _P	Positive Threshold Voltage		0.9	–	0.62	–	–	–	V
			1.1	–	–	1.0	–	1.0	
			1.4	–	–	1.2	–	1.2	
			1.65	–	–	1.5	–	1.5	
			2.3	–	–	1.9	–	1.9	
			3.0	–	–	2.6	–	2.6	
V _N	Negative Threshold Voltage		0.9	–	0.34	–	–	–	V
			1.1	0.15	–	–	0.15	–	
			1.4	0.2	–	–	0.2	–	
			1.65	0.25	–	–	0.25	–	
			2.3	0.4	–	–	0.4	–	
			3.0	0.6	–	–	0.6	–	
V _H	Hysteresis Voltage		0.9	–	0.29	–	–	–	V
			1.1	0.08	–	0.6	0.08	0.6	
			1.4	0.09	–	0.8	0.09	0.8	
			1.65	0.1	–	1.0	0.1	1.0	
			2.3	0.25	–	1.1	0.25	1.1	
			3.0	0.6	–	1.8	0.6	1.8	
V _{OH}	High-Level Output Voltage	V _{IN} = V _P or V _N							V
		I _{OH} = -20 µA	0.9	–	V _{CC} - 0.1	–	–	–	
			1.1 to 1.3	V _{CC} - 0.1	–	–	V _{CC} - 0.1	–	
			1.4 to 1.6	V _{CC} - 0.1	–	–	V _{CC} - 0.1	–	
			1.65 to 1.95	V _{CC} - 0.1	–	–	V _{CC} - 0.1	–	
			2.3 to 2.7	V _{CC} - 0.1	–	–	V _{CC} - 0.1	–	
			3.0 to 3.6	V _{CC} - 0.1	–	–	V _{CC} - 0.1	–	
		I _{OH} = -0.5 mA	1.1 to 1.3	0.75 x V _{CC}	–	–	0.75 x V _{CC}	–	
			1.4 to 1.6	1.07	–	–	0.99	–	
		I _{OH} = -1 mA	1.65 to 1.95	1.24	–	–	1.22	–	
		I _{OH} = -1.5 mA	2.3 to 2.7	1.95	–	–	1.87	–	
		I _{OH} = -2.1 mA	3.0 to 3.6	2.61	–	–	2.55	–	



DC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			T _A = -40°C to +85°C		Unit
				Min	Typ	Max	Min	Max	
V _{OL}	Low-Level Output Voltage	V _{IN} = V _P or V _N							V
		I _{OL} = 20 µA	0.9	–	0.1	–	–	–	
			1.1 to 1.3	–	–	0.1	–	0.1	
			1.4 to 1.6	–	–	0.1	–	0.1	
			1.65 to 1.95	–	–	0.1	–	0.1	
			2.3 to 2.7	–	–	0.1	–	0.1	
			3.0 to 3.6	–	–	0.1	–	0.1	
		I _{OL} = 0.5 mA	1.1 to 1.3	–	–	0.3 x V _{CC}	–	0.3 x V _{CC}	
		I _{OL} = 1 mA	1.4 to 1.6	–	–	0.31	–	0.37	
		I _{OL} = 1.5 mA	1.65 to 1.95	–	–	0.31	–	0.35	
		I _{OL} = 2.1 mA	2.3 to 2.7	–	–	0.31	–	0.33	
		I _{OL} = 2.6 mA	3.0 to 3.6	–	–	0.31	–	0.33	
I _{IN}	Input Leakage Current	V _{IN} = 0 V to 3.6 V	0.9 to 3.6	–	–	±0.1	–	±0.5	µA
I _{OFF}	Power Off Leakage Current	V _{IN} = 0 V to 3.6 V or V _{OUT} = 0 V to 3.6 V	0	–	–	0.5	–	0.5	µA
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	0.9 to 3.6	–	–	0.9	–	0.9	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

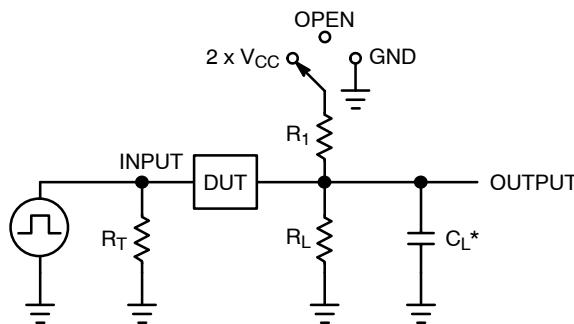
Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			T _A = -40°C to +85°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	R _L = 1 MΩ, C _L = 10 pF	0.9	–	64.4	–	–	–	ns
			1.10 to 1.30	–	16.4	39.3	–	46.6	
			1.40 to 1.60	–	6.7	14.8	–	15.0	
			1.65 to 1.95	–	4.7	12.0	–	12.2	
			2.3 to 2.7	–	3.2	9.4	–	9.9	
			3.0 to 3.6	–	2.6	8.3	–	9.0	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	R _L = 1 MΩ, C _L = 15 pF	0.9	–	66.3	–	–	–	ns
			1.10 to 1.30	–	16.9	40.7	–	48.2	
			1.40 to 1.60	–	7.1	15.5	–	16.5	
			1.65 to 1.95	–	5.1	12.6	–	13.6	
			2.3 to 2.7	–	3.4	9.9	–	10.8	
			3.0 to 3.6	–	2.8	8.7	–	9.5	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	R _L = 1 MΩ, C _L = 30 pF	0.9	–	72.1	–	–	–	ns
			1.10 to 1.30	–	18.3	44.9	–	53.0	
			1.40 to 1.60	–	8.4	17.8	–	18.2	
			1.65 to 1.95	–	6.2	14.4	–	15.9	
			2.3 to 2.7	–	4.1	11.3	–	12.8	
			3.0 to 3.6	–	3.3	9.2	–	10.7	



CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical ($T_A = 25^\circ\text{C}$)	Unit
C_{IN}	Input Capacitance	$V_{CC} = 0\text{ V}$	2.0	pF
C_{OUT}	Output Capacitance	$V_{CC} = 0\text{ V}$	4.0	pF
C_{PD}	Power Dissipation Capacitance (Note 5)	$f = 10\text{ MHz}, V_{CC} = 0.9\text{ to }3.6\text{ V}, V_{IN} = 0\text{ V or }V_{CC}$	8.0	pF

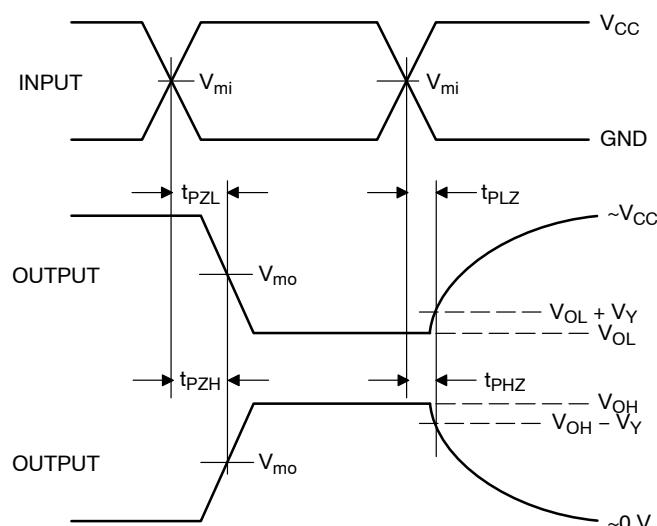
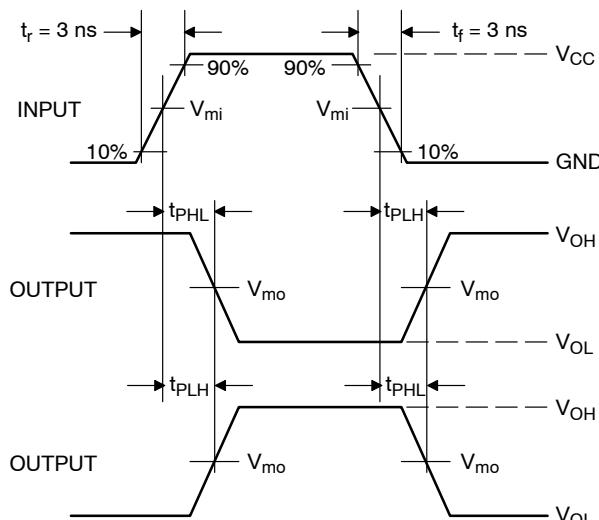
5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.



C_L includes probe and jig capacitance
 R_T is Z_{OUT} of pulse generator (typically $50\ \Omega$)
 $f = 1\text{ MHz}$

Test	Switch Position
t_{PLH} / t_{PHL}	Open
t_{PLZ} / t_{PZL}	$2 \times V_{CC}$
t_{PHZ} / t_{PZH}	GND

Figure 3. Test Circuit



V_{CC}, V	V_{mi}, V	V_{mo}, V	V_Y, V
0.9	$V_{CC} / 2$	$V_{CC} / 2$	0.1
1.1 to 1.3	$V_{CC} / 2$	$V_{CC} / 2$	0.1
1.4 to 1.6	$V_{CC} / 2$	$V_{CC} / 2$	0.1
1.65 to 1.95	$V_{CC} / 2$	$V_{CC} / 2$	0.15
2.3 to 2.7	$V_{CC} / 2$	$V_{CC} / 2$	0.15
3.0 to 3.6	1.5	1.5	0.3

Figure 4. Switching Waveforms

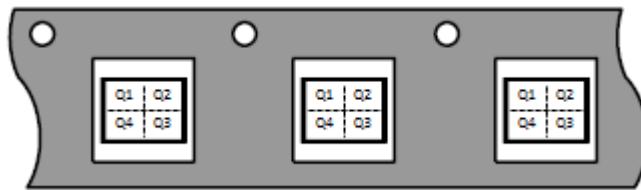
ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NC7SP17P5X	SC-88A	P17	Q4	3000 / Tape & Reel
NC7SP17L6X	MicroPak	K4	Q4	5000 / Tape & Reel
NC7SP17FHX	MicroPak2	K4	Q4	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PIN 1 ORIENTATION IN TAPE AND REEL

Direction of Feed

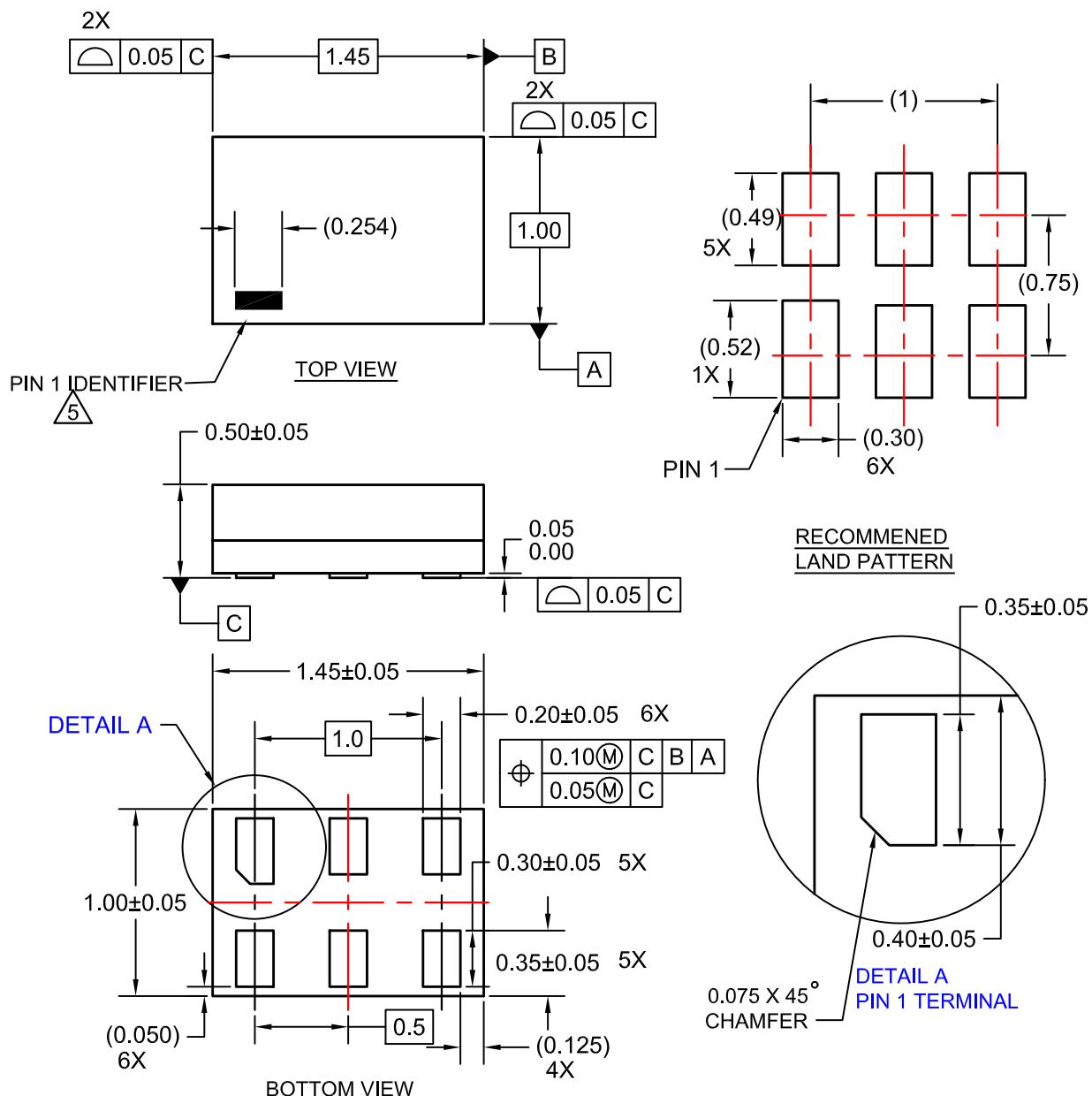


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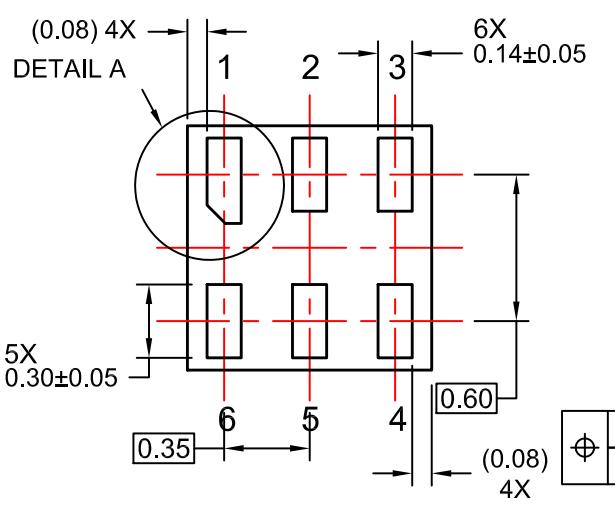
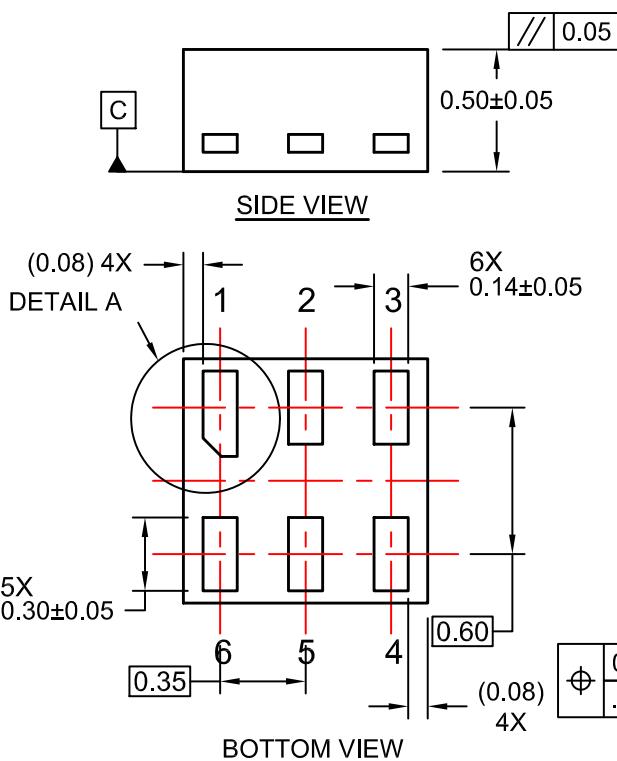
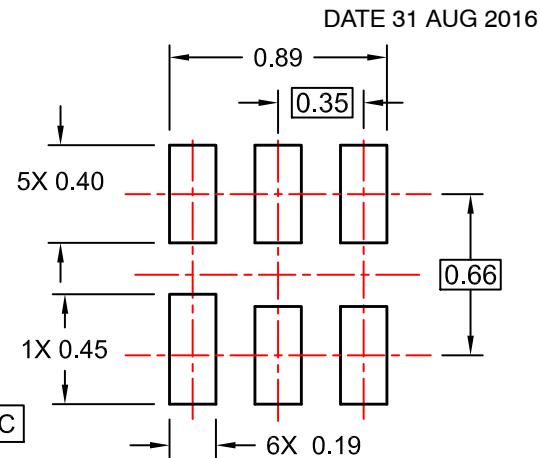
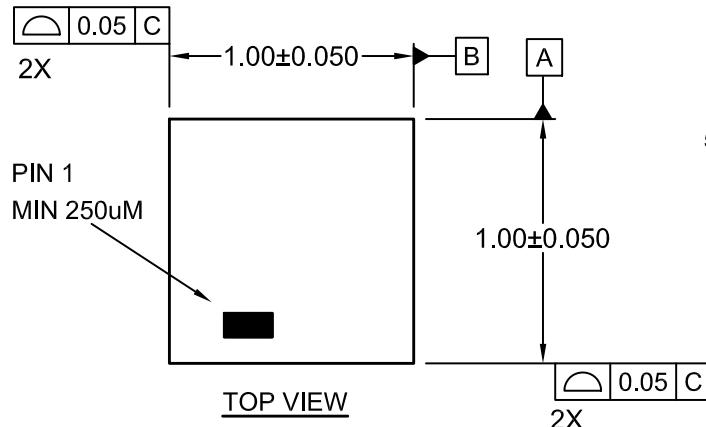
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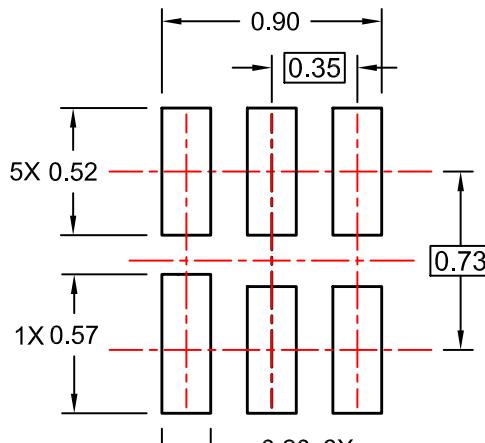
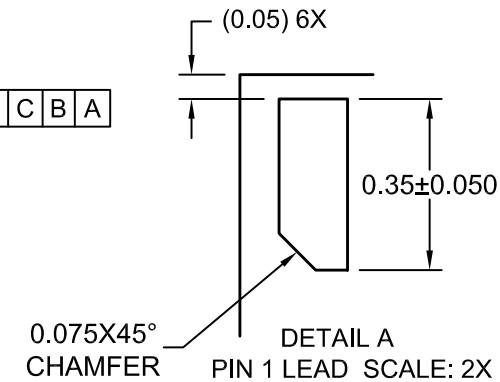
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NOTES:

A. COMPLIES TO JEDEC MO-252 STANDARD
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009

RECOMMENDED LAND PATTERN
FOR SPACE CONSTRAINED PCBALTERNATIVE LAND PATTERN
FOR UNIVERSAL APPLICATION

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